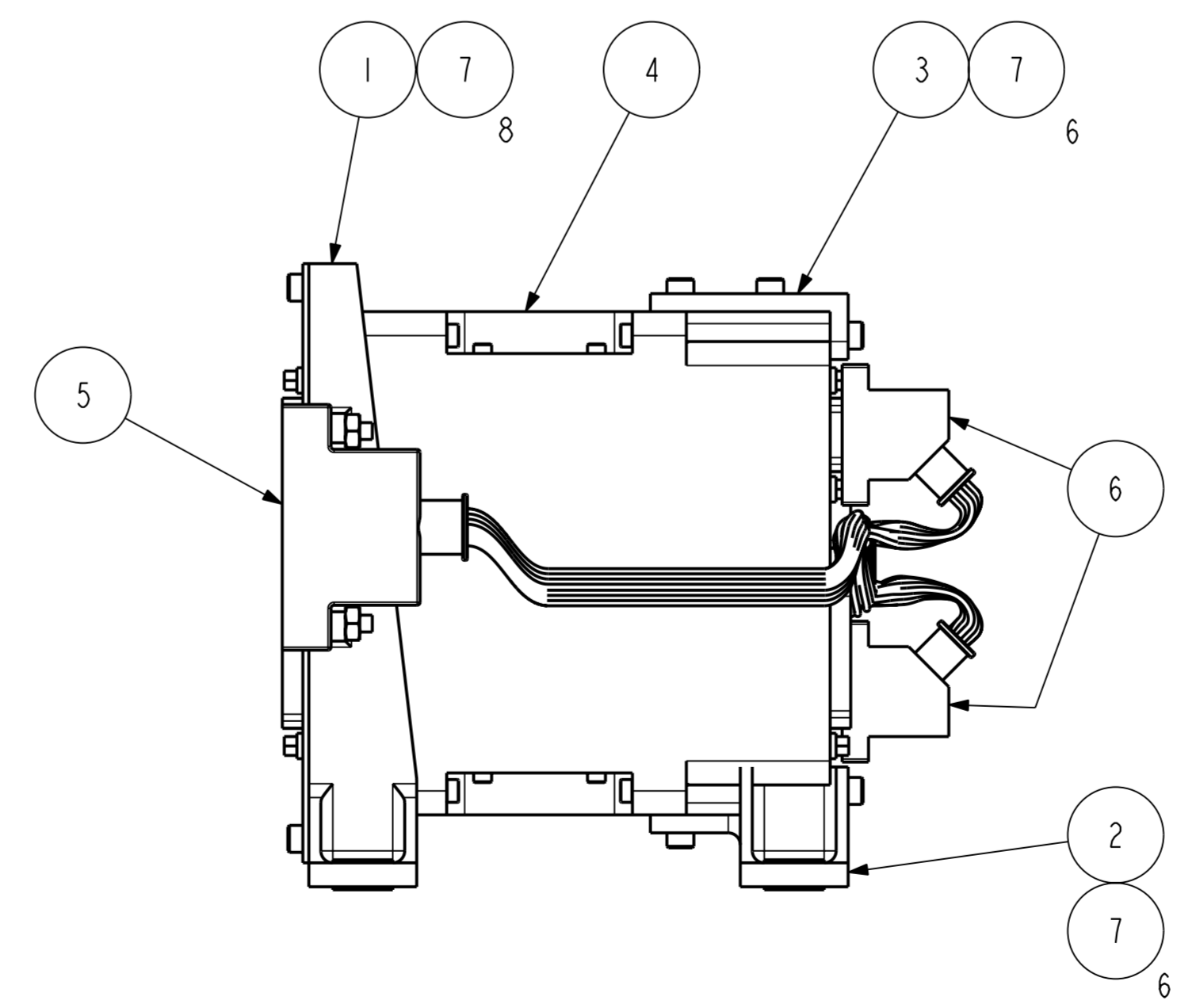


No.	DESCRIPTION	QTY	MASS (g) / ITEM	MASS (g) TOTAL	REMARKS
1	FRONT PLATE	1	36.0	36.0	
2	LOWER BACK PLATE	1	6.6	6.6	
3	UPPER BACK PLATE	1	23.0	23.0	
4	JFET MODULE	2	305	610	
5	37 WAY MICRO-D	2	17.0	34.0	CONNECTOR AND BACKPLATE
6	15 WAY MICRO-D	4	8.3	33.2	CONNECTOR AND BACKPLATE
7	CP.HD SCREW	20	0.6	12.0	M2.5 x 8 LONG
8	CP.HD SCREW	4	3.0	12.0	M4 x 20 LONG
9	WASHER	4	3.1	12.4	M4
10	TOP INSULATOR	4	0.04	0.16	VESPEL
11	BOTTOM INSULATOR	4	0.09	0.36	VESPEL
GRAND TOTAL				779.7	

NOTE
ITEMS 10 & 11 TO BE PERMANENTLY BONDED TO FEET



MASTER DRAWING	
PROJECT MEMBER	APPROVED
PROJECT MANAGER	
SYSTEM ENG	
ELECTRONICS ENG	
PA GROUP	
STRESS ENG	
OPTICAL ENG	
THERMAL ENG	
MECHANICAL ENG	

B	30-NOV-01	KE-2897	T.R.F			PROV.
ISSUE	DATE	MOD. No.	DRN. BY	CHKD.	APPD.	STATUS
TOLERANCES UNLESS STATED ±0.2 mm ±0.3			FINISH CLEAN REMOVE ALL BURRS		ORIGINAL SCALE 1:1 DO NOT SCALE	
MATERIAL & SPEC. SEE DETAILS			SURFACE TEXTURE µm SEE DETAILS ✓UNLESS STATED		0 50mm	
USED ON						©CLRC 2001
CENTRAL LABORATORY OF THE RESEARCH COUNCILS						
TITLE 2 JFET ASSEMBLY						
A 0-JFET_RACK_2JFETS I-0B1						

FOR INFORMATION ONLY